

V_{DSS}	-12V
$R_{DS(on)(Max.)}$	12m Ω
I_D	$\pm 7A$
P_D	1.5W

●Features

- 1) Low on - resistance.
- 2) Low voltage drive(1.5V).
- 3) High power package.

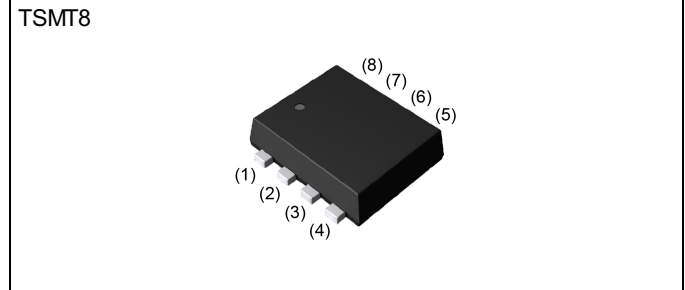
●Application

Switching

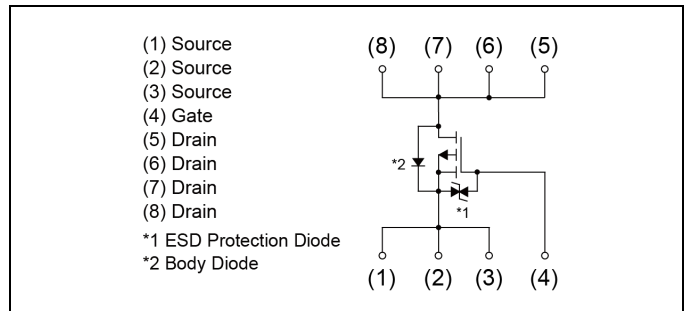
●Absolute maximum ratings ($T_a = 25^\circ C$)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V_{DSS}	-12	V
Continuous drain current	I_D	± 7	A
Pulsed drain current	$I_{D,pulse}^{*1}$	± 28	A
Gate - Source voltage	V_{GSS}	± 10	V
Power dissipation	P_D^{*2}	1.5	W
	P_D^{*3}	0.7	W
Junction temperature	T_j	150	$^\circ C$
Range of storage temperature	T_{stg}	-55 to +150	$^\circ C$

●Outline



●Inner circuit



●Packaging specifications

Type	Packing	Embossed Tape
	Reel size (mm)	180
Tape width (mm)	8	
Basic ordering unit (pcs)	3000	
Taping code	TR	
Marking	YJ	

● Thermal resistance

Parameter	Symbol	Values			Unit
		Min.	Typ.	Max.	
Thermal resistance, junction - ambient	R_{thJA}^{*2}	-	-	83.3	°C/W
	R_{thJA}^{*3}	-	-	178	°C/W

● Electrical characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -1mA$	-12	-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$	$I_D = -1mA$ referenced to 25°C	-	-21.9	-	mV/°C
Zero gate voltage drain current	I_{DSS}	$V_{DS} = -12V, V_{GS} = 0V$	-	-	-1	μA
Gate - Source leakage current	I_{GSS}	$V_{GS} = \pm 10V, V_{DS} = 0V$	-	-	± 10	μA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = -6V, I_D = -1mA$	-0.3	-	-1.0	V
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	$I_D = -1mA$ referenced to 25°C	-	2.4	-	mV/°C
Static drain - source on - state resistance	$R_{DS(on)}^{*4}$	$V_{GS} = -4.5V, I_D = -7A$	-	8	12	m Ω
		$V_{GS} = -2.5V, I_D = -3.5A$	-	11	16	
		$V_{GS} = -1.8V, I_D = -3.5A$	-	15	23	
		$V_{GS} = -1.5V, I_D = -1.4A$	-	19	38	
Forward Transfer Admittance	$ Y_{fs} ^{*4}$	$V_{DS} = -6V, I_D = -7A$	12	-	-	S

*1 $P_w \leq 10\mu\text{s}$, Duty cycle $\leq 1\%$

*2 Mounted on a ceramic board (30×30×0.8mm)

*3 Mounted on a FR4(20×20×0.8mm)

*4 Pulsed

●Electrical characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Input capacitance	C _{iss}	V _{GS} = 0V	-	7400	-	pF
Output capacitance	C _{oss}	V _{DS} = -6V	-	800	-	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	750	-	
Turn - on delay time	t _{d(on)} ^{*4}	V _{DD} ≈ -6V, V _{GS} = -4.5V	-	35	-	ns
Rise time	t _r ^{*4}	I _D = -3.5A	-	95	-	
Turn - off delay time	t _{d(off)} ^{*4}	R _L ≈ 1.7Ω	-	310	-	
Fall time	t _f ^{*4}	R _G = 10Ω	-	190	-	

●Gate charge characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Total gate charge	Q _g ^{*4}	V _{DD} ≈ -6V,	-	58	-	nC
Gate - Source charge	Q _{gs} ^{*4}	I _D = -7A,	-	11	-	
Gate - Drain charge	Q _{gd} ^{*4}	V _{GS} = -4.5V	-	10	-	

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Body diode continuous forward current	I _S	T _a = 25°C	-	-	-1	A
Body diode pulse current	I _{SP} ^{*1}		-	-	-28	A
Forward voltage	V _{SD} ^{*4}	V _{GS} = 0V, I _S = -7A	-	-	-1.2	V

● Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

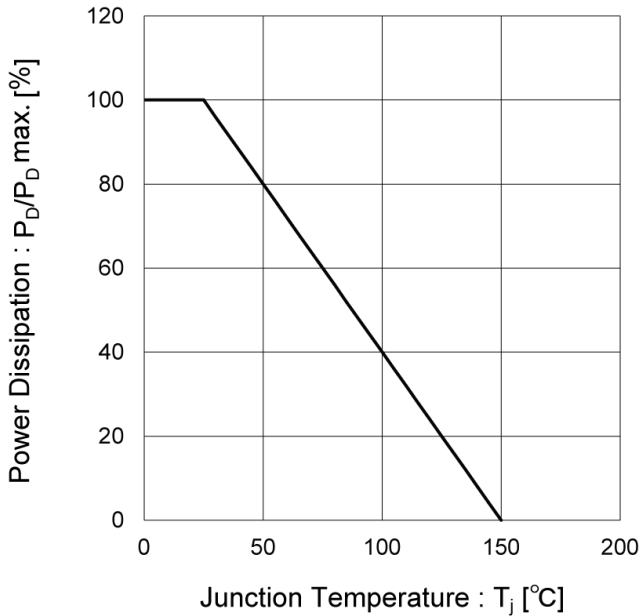


Fig.2 Maximum Safe Operating Area

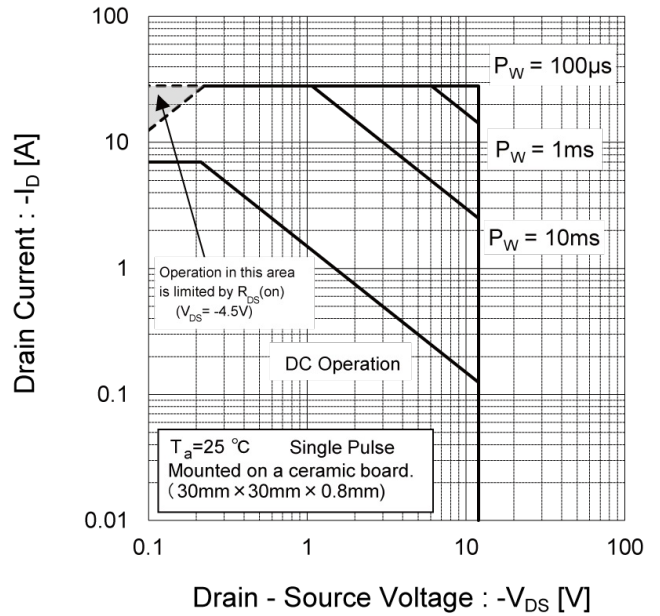


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

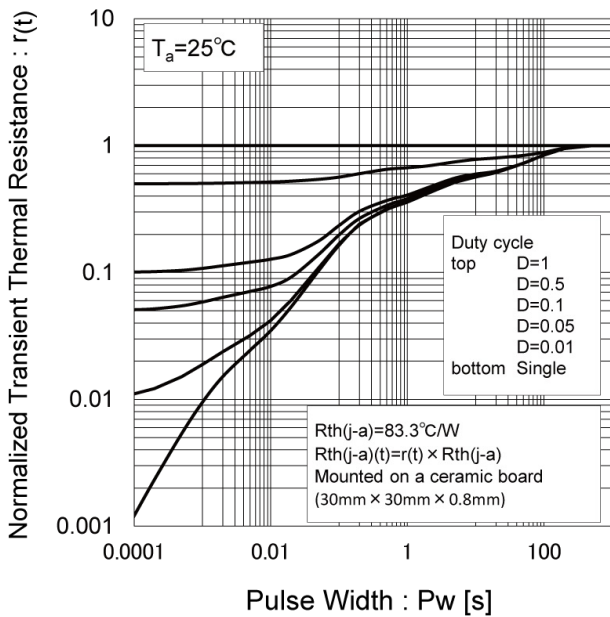
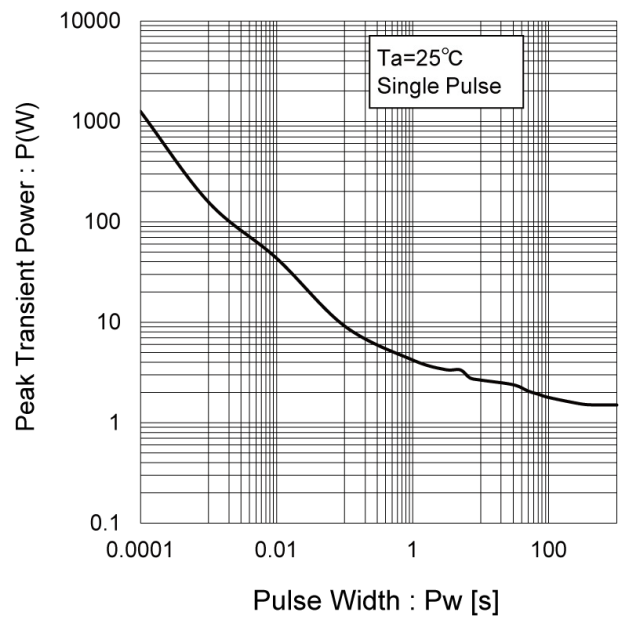


Fig.4 Single Pulse Maximum Power dissipation



● Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)

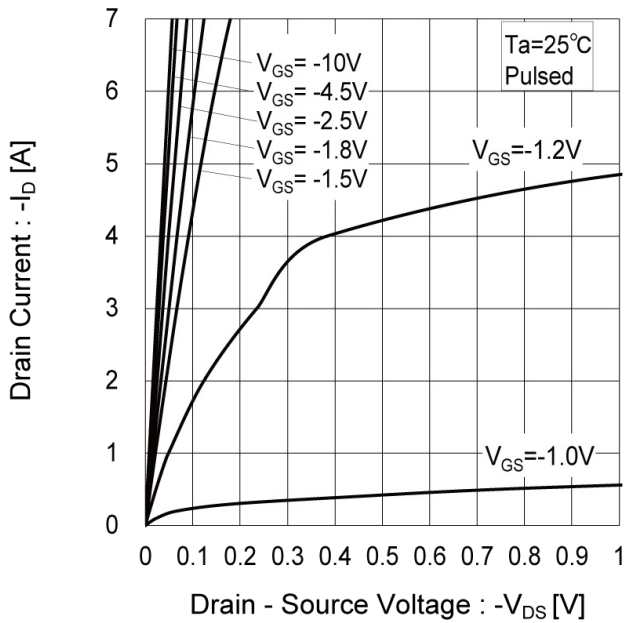


Fig.6 Typical Output Characteristics(II)

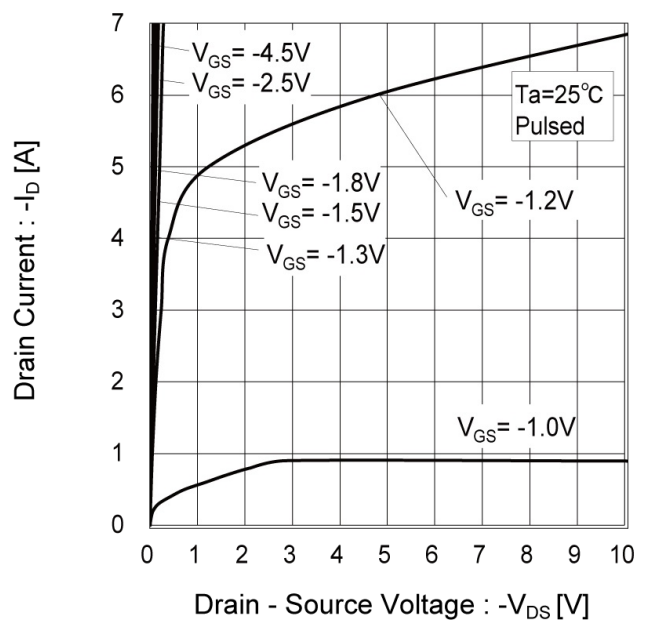


Fig.7 Breakdown Voltage vs. Junction Temperature

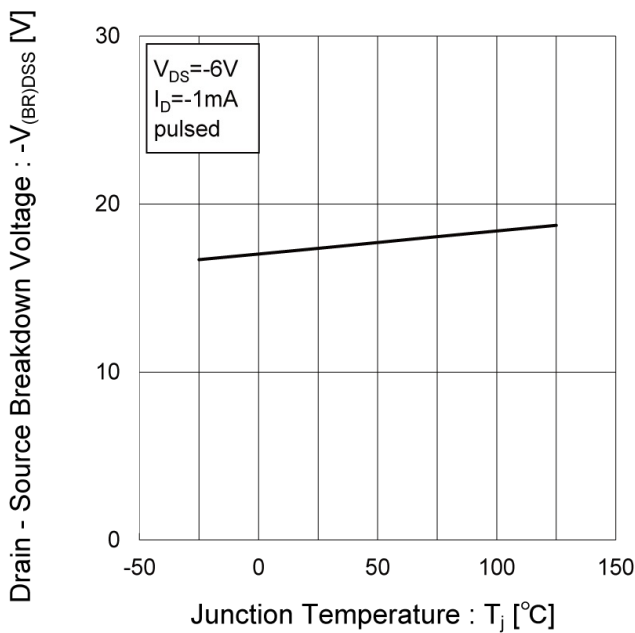
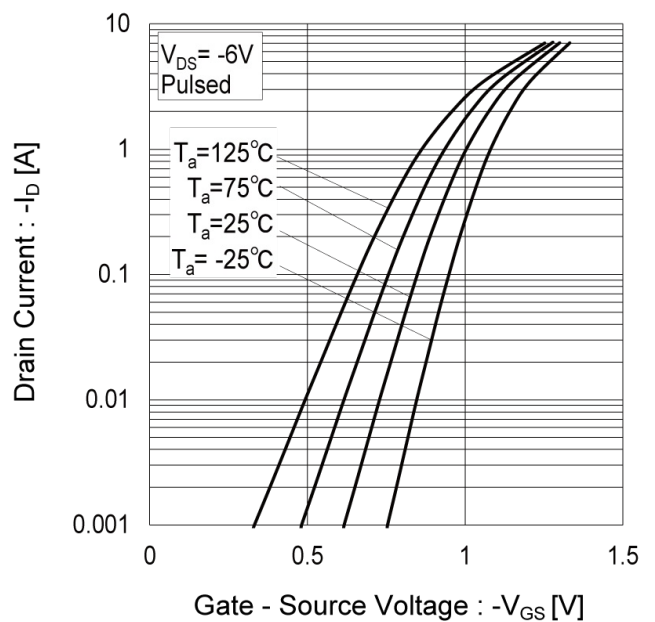


Fig.8 Typical Transfer Characteristics



● Electrical characteristic curves

Fig.9 Gate Threshold Voltage vs. Junction Temperature

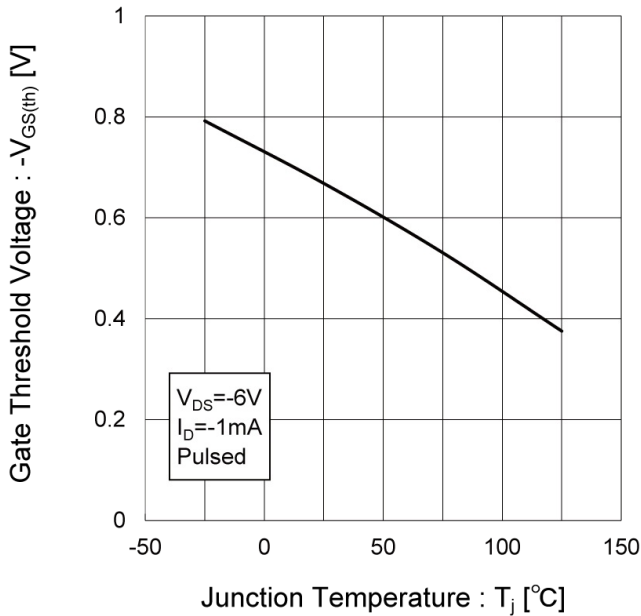


Fig.10 Forward Transfer Admittance vs. Drain Current

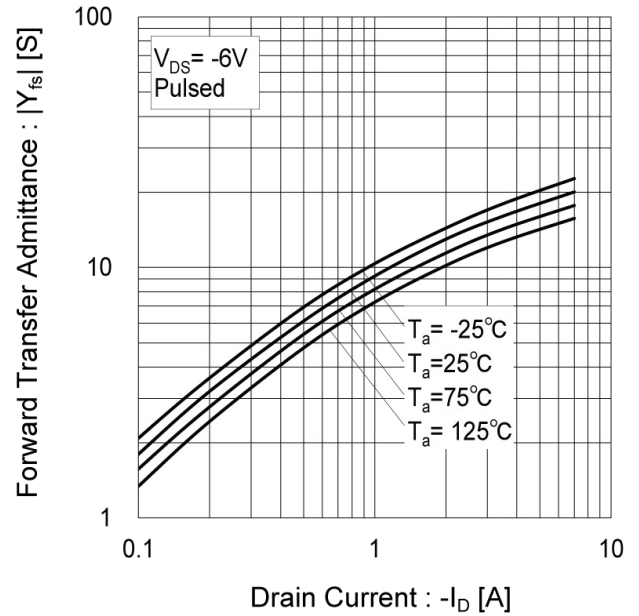


Fig.11 Drain Current Derating Curve

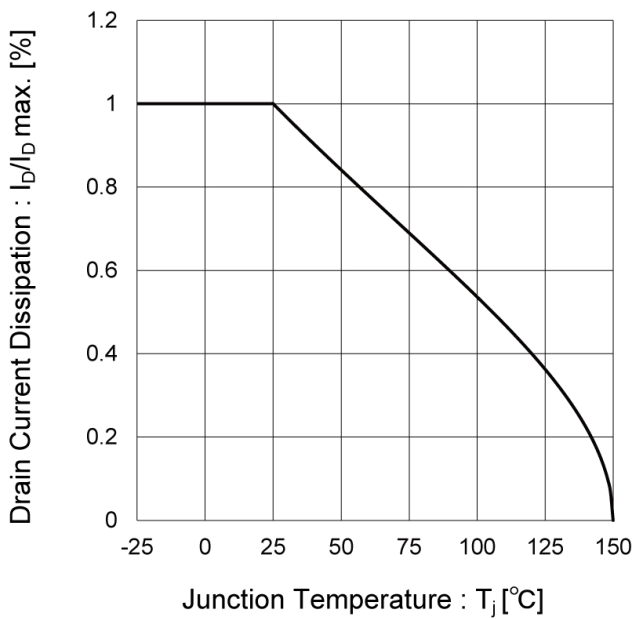
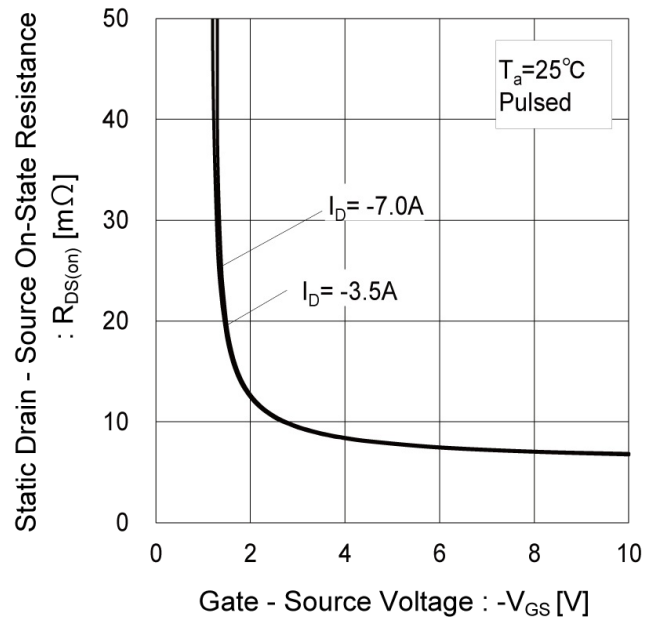


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



● Electrical characteristic curves

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

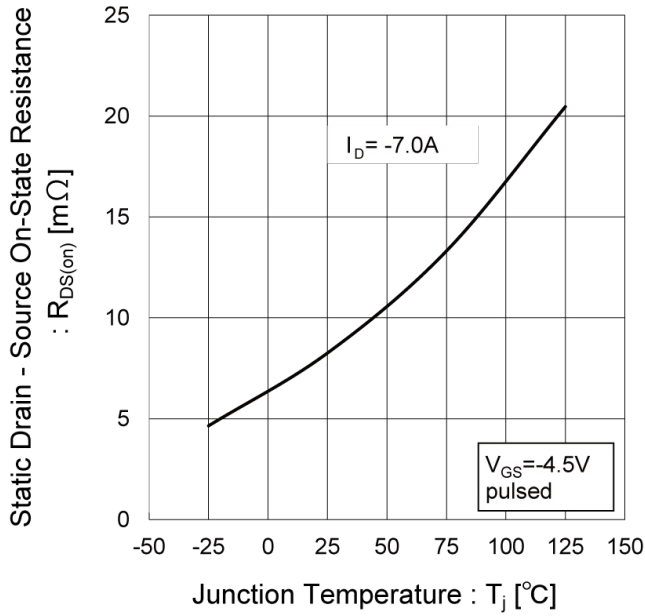
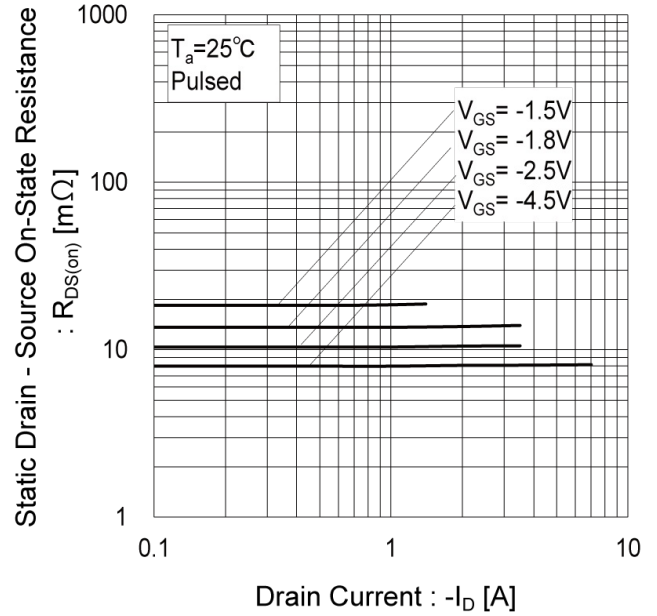


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)



● Electrical characteristic curves

Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

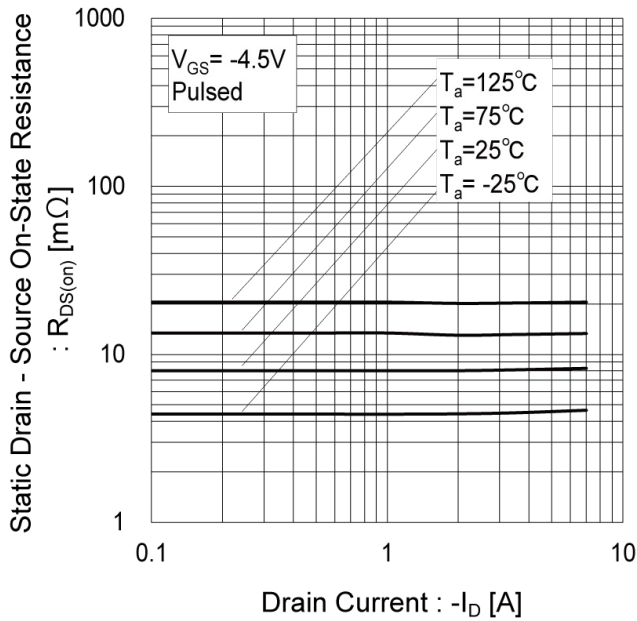


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

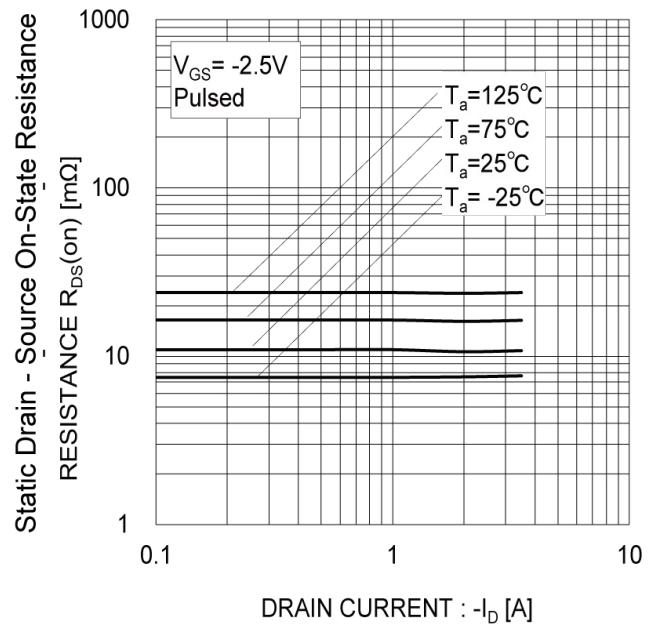


Fig.17 Static Drain - Source On - State Resistance vs. Drain Current (IV)

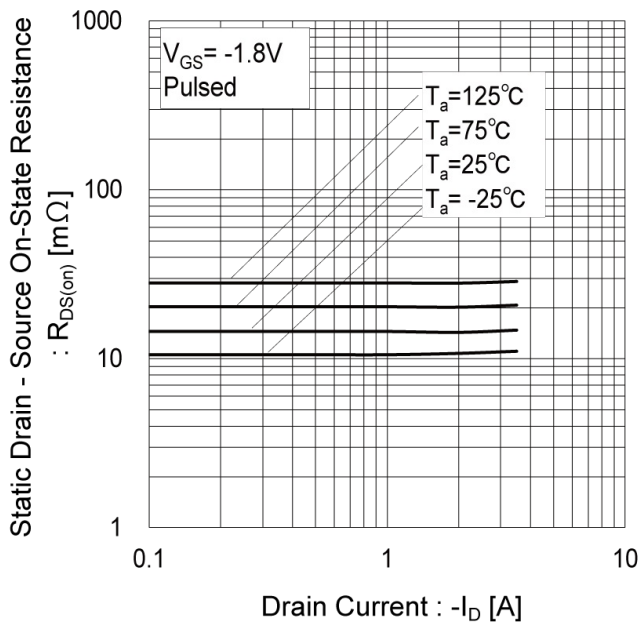
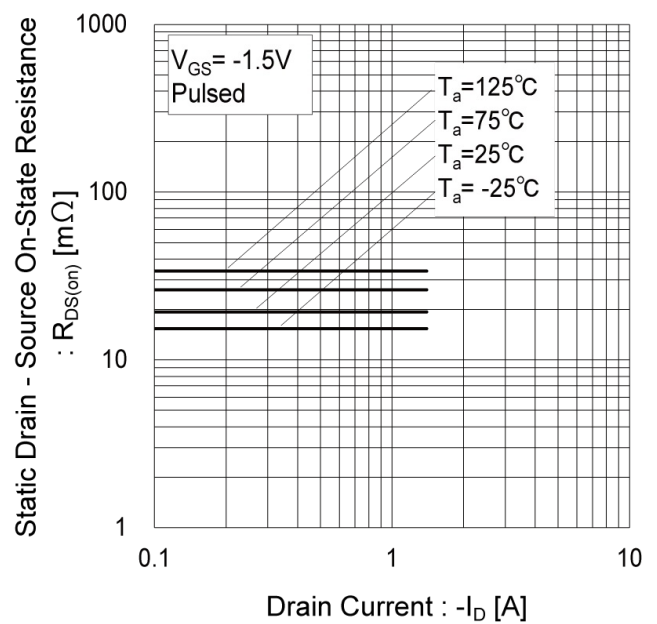


Fig.18 Static Drain - Source On - State Resistance vs. Drain Current(V)



● Electrical characteristic curves

Fig.19 Typical Capacitance vs. Drain - Source Voltage

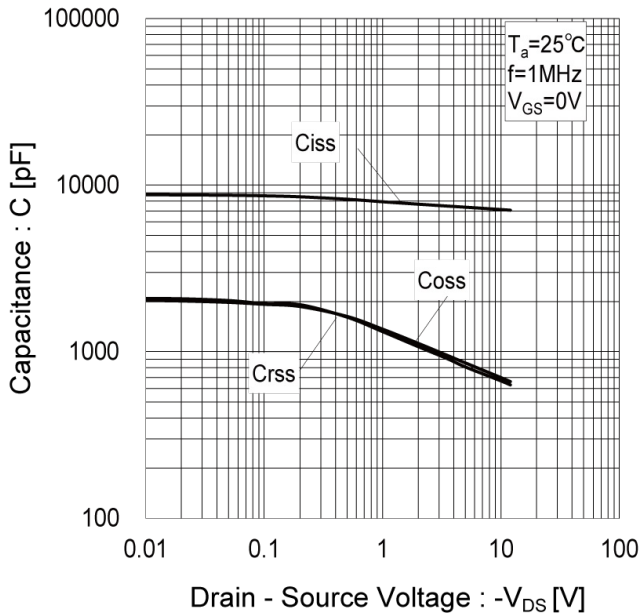


Fig.20 Switching Characteristics

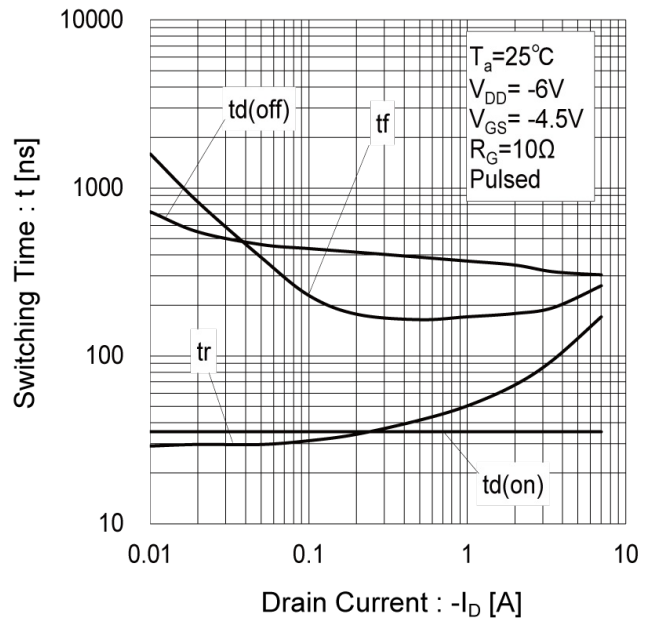


Fig.21 Dynamic Input Characteristics

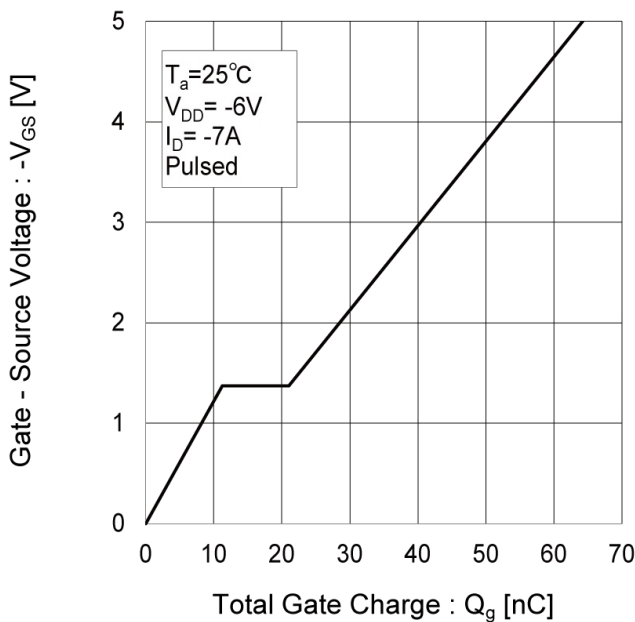
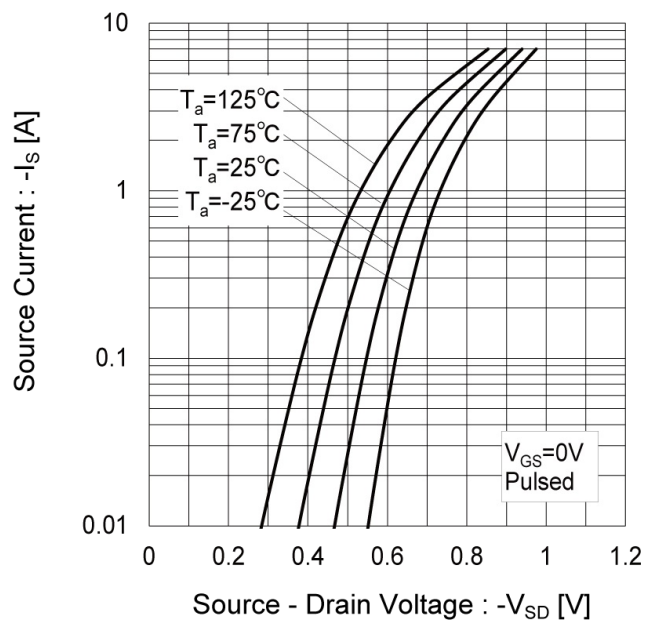


Fig.22 Source Current vs. Source Drain Voltage



● Measurement circuits

Fig. 1-1 SWITCHING TIME MEASUREMENT CIRCUIT

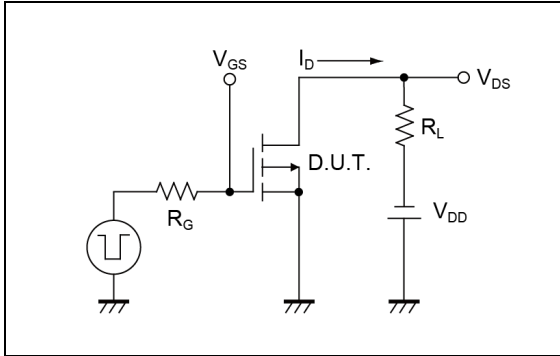


Fig. 1-2 SWITCHING WAVEFORMS

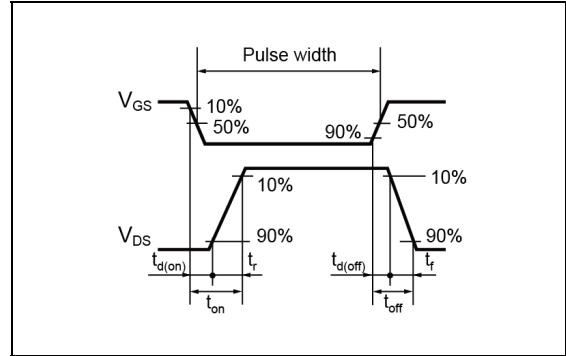


Fig. 2-1 GATE CHARGE MEASUREMENT CIRCUIT

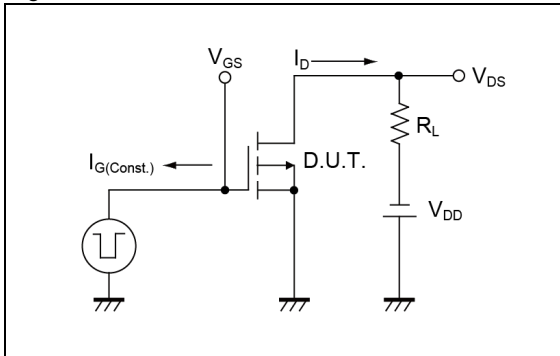
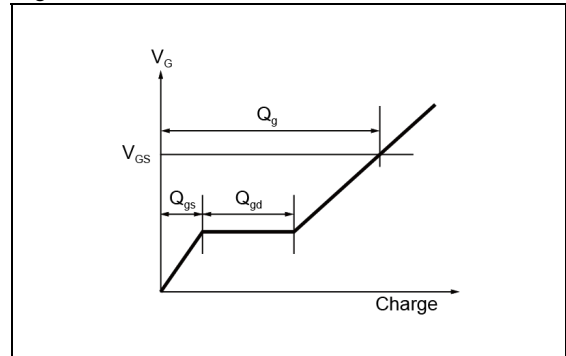


Fig. 2-2 GATE CHARGE WAVEFORM

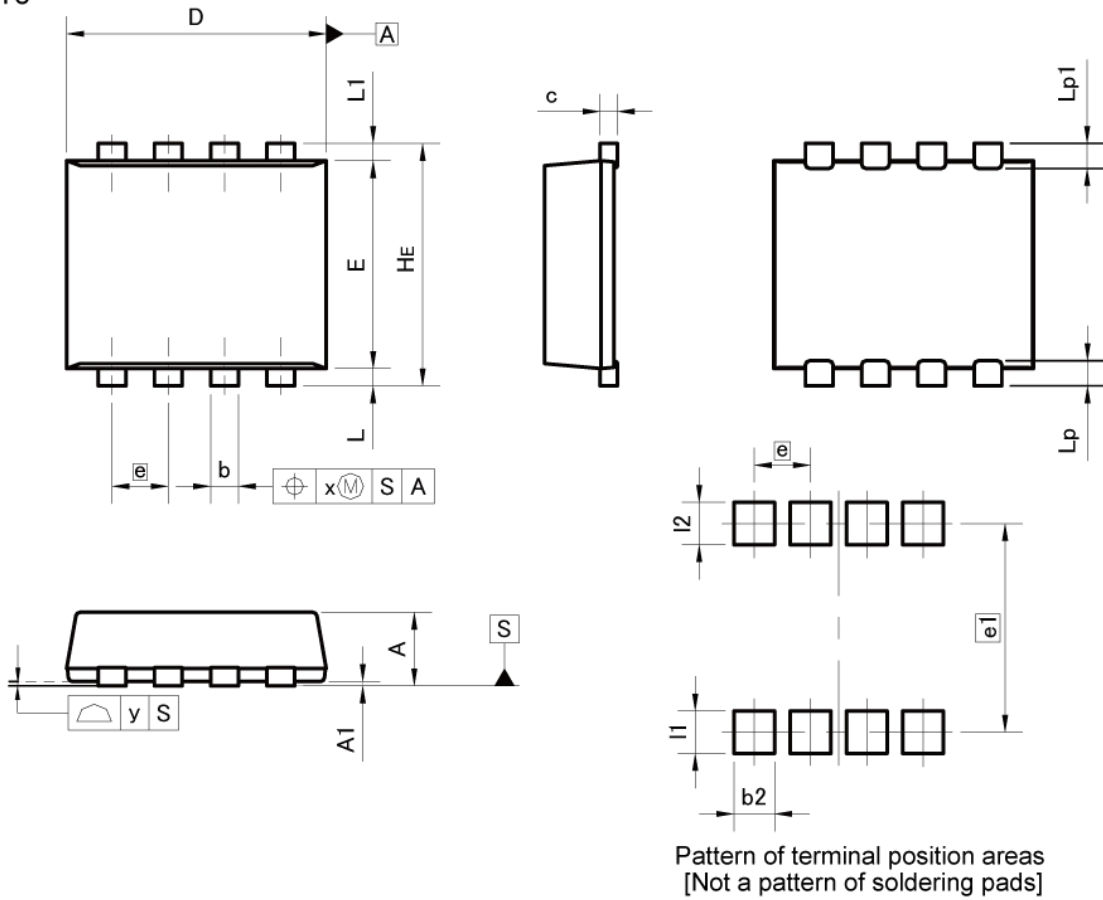


● Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

●Dimensions

TSMT8



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.75	0.85	0.030	0.033
A1	0.00	0.05	0.000	0.002
b	0.27	0.37	0.011	0.015
c	0.12	0.22	0.005	0.009
D	2.90	3.10	0.114	0.122
E	2.30	2.50	0.091	0.098
e	0.65		0.026	
HE	2.70	2.90	0.106	0.114
L	0.10	0.30	0.004	0.012
L1	0.10	0.30	0.004	0.012
Lp	0.19	0.39	0.007	0.015
Lp1	0.19	0.39	0.007	0.015
x	-	0.10	-	0.004
y	-	0.10	-	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	-	0.47	-	0.019
e1	2.41		0.095	
I1	-	0.49	-	0.019
I2	-	0.49	-	0.019

Dimension in mm/inches

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